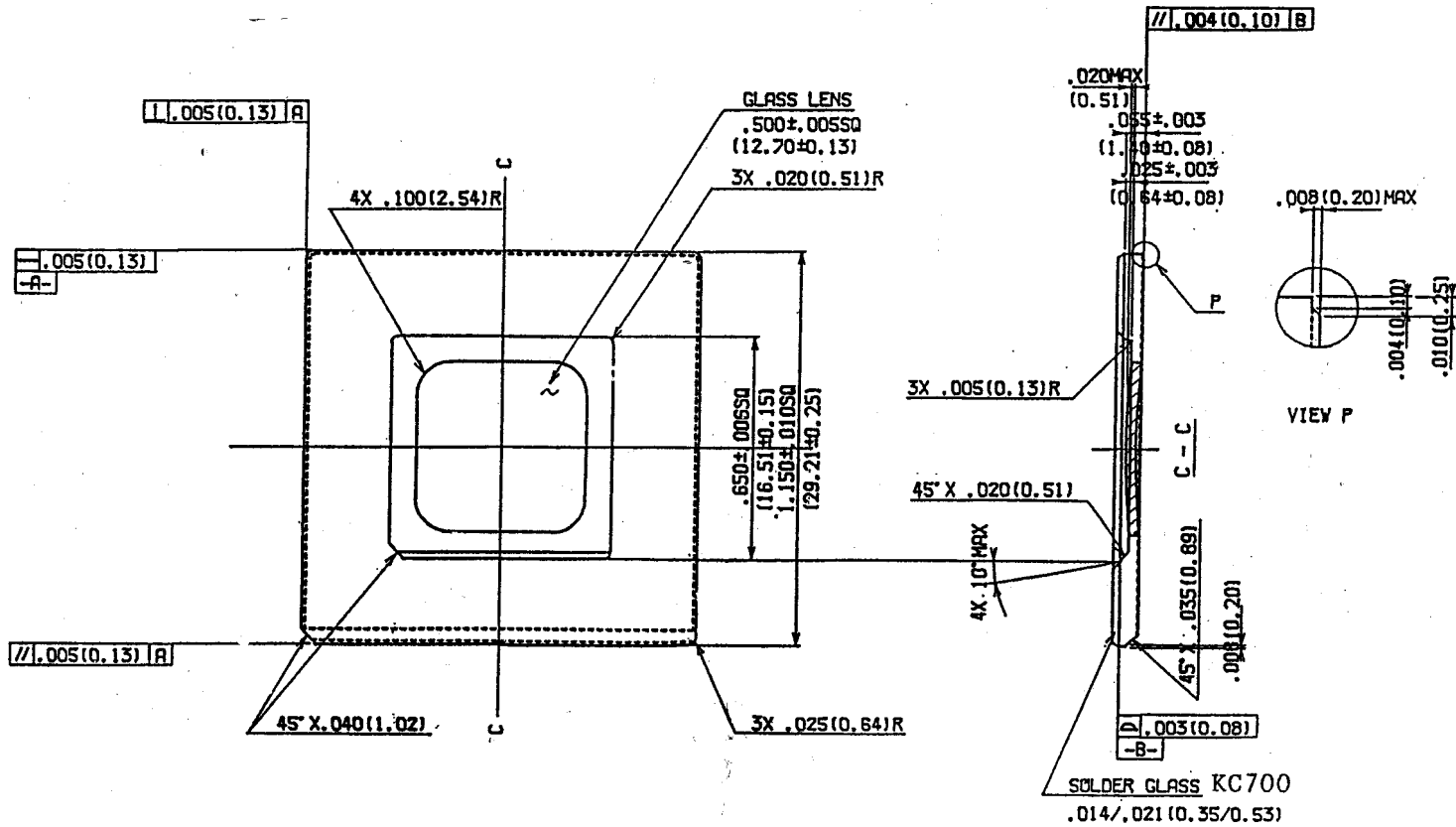


SSM P/N CQC08404



NAME		TOLERANCES: UNLESS OTHERWISE SPECIFIED	INCH(mm)	
84LD CERQUAD EPROMCAP 500SQ			DRAWN	CHECKED
SCALE	MATERIAL		<i>Robert D</i>	<i>Shaw</i>
FREE	Al ₂ O ₃ 90%MIN(BLACK)		APPROVED	DATE
			<i>Robert D</i>	OCT. 03' 89
KYOCERA CORPORATION		KYOTO JAPAN	DWG. # KKC-10831	



1. CHARACTERISTICS

Transition Point (°C)	308
Deformation Point (°C)	324
Softening Point (°C)	342
Thermal Expansion Coefficient	
40-250°C (x 10 ⁻⁶ /°C)	6.8
Specific Gravity (g/cc)	5.6
Dielectric Constant 1MHz, 25°C	12.5
Volume Resistivity	
log ₁₀ (Ω-cm) at 250°C	9.4
Dielectric Loss Tangent	
1 MHz, 25°C	0.003
Acid Durability (mg/cm ²)	
1N HCL 25°C 5 min.	0.7
18N H ₂ SO ₄ 50°C, 5 min.	0.1
Thermal Conductivity	
25°C (Cal/cm. sec. °C)	0.0028
Alpha Emission	
(α/cm ² /hr.)	0.6

2. RECOMMENDED PRE-CLEANING

Steps	Solution	Temp.	Period
a. De-scaling	50% H ₂ SO ₄	75°C - 95°C	1 min.
b. Tap water rinse		25°C	2 min. min.
c. Acid washing	10% H ₂ SO ₄	25°C	10 seconds
d. Tap water rinse		25°C	2 min. min.
e. Distilled water rinse		25°C	2 min. min.
f. Tin plating		(see below)	

3. RECOMMENDED TIN PLATING CONDITION
3.1 Plating Solution

- Sulphuric Acid Bath

105 cc/liter

30 gram/liter

40 cc/liter

H₂SO₄

SnSO₄

Tinglo Culmo Starter Conc.

- Temperature of Plating Bath 17-21°C

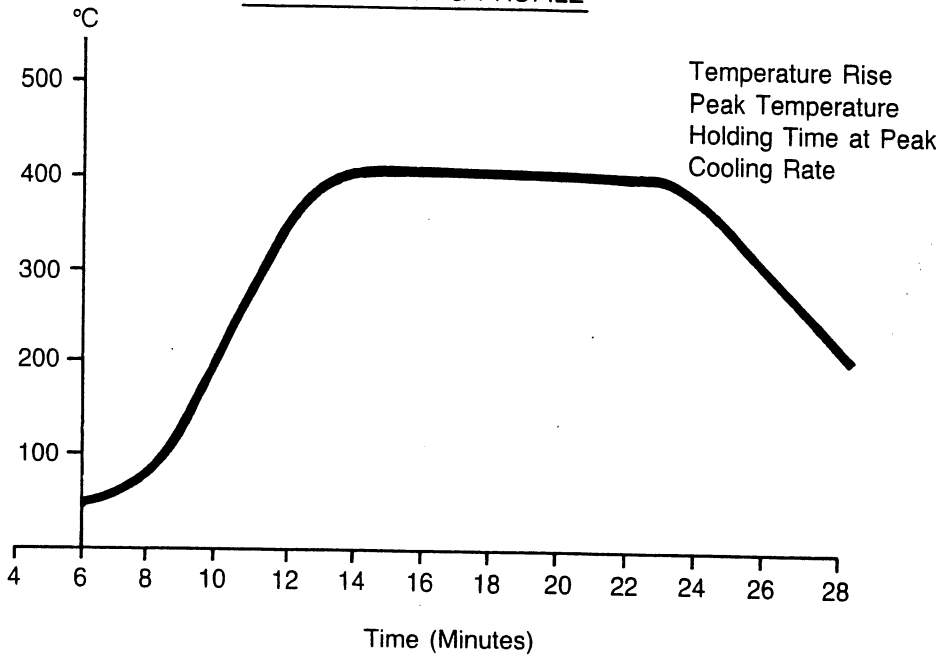
3.2 Current Density – 1.4-2.5 Ampere/SQ DM (Square Decimeter)

3.3 Plating Time 10 Minutes Max.



KC-700 DATA SHEET

TYPICAL SEALING PROFILE



Temperature Rise 40-90°C/Min
Peak Temperature 425-440°C
Holding Time at Peak 6-11 minutes
Cooling Rate 20-40°C/min.